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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	32-Bit Single-Core
Speed	66MHz
Connectivity	EBI/EMI, Ethernet, I²C, SPI, SSC, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	109
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at32uc3a0128-alur

Table 6-1. TQFP100 Package Pinout

23	PA02	**48**	DM	**73**	PB05	**98**	PB17
24	PA03	**49**	DP	**74**	PB06	**99**	PB18
25	PA04	**50**	GND	**75**	PB07	**100**	PB19

Figure 6-2. LQFP144 Pinout

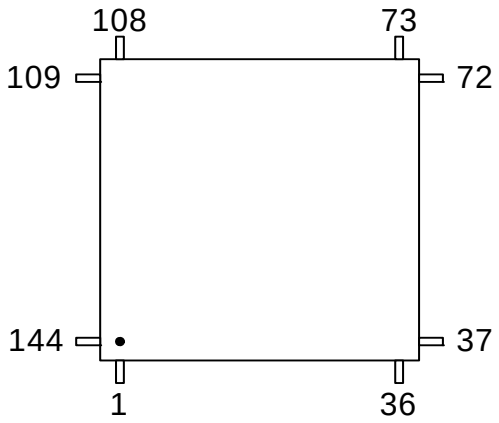


Table 6-2. VQFP144 Package Pinout

1	PX00	**37**	GND	**73**	PA21	**109**	GND
2	PX01	**38**	PX10	**74**	PA22	**110**	PX30
3	PB20	**39**	PA05	**75**	PA23	**111**	PB08
4	PX02	**40**	PX11	**76**	PA24	**112**	PX31
5	PB21	**41**	PA06	**77**	PA25	**113**	PB09
6	PB22	**42**	PX12	**78**	PA26	**114**	PX32
7	VDDIO	**43**	PA07	**79**	PA27	**115**	PB10
8	GND	**44**	PX13	**80**	PA28	**116**	VDDIO
9	PB23	**45**	PA08	**81**	VDDANA	**117**	GND
10	PX03	**46**	PX14	**82**	ADVREF	**118**	PX33
11	PB24	**47**	PA09	**83**	GNDANA	**119**	PB11
12	PX04	**48**	PA10	**84**	VDDPLL	**120**	PX34
13	PB25	**49**	N/C	**85**	PC00	**121**	PB12
14	PB26	**50**	PA11	**86**	PC01	**122**	PA29
15	PB27	**51**	VDDCORE	**87**	PX20	**123**	PA30
16	VDDOUT	**52**	GND	**88**	PB00	**124**	PC02
17	VDDIN	**53**	PA12	**89**	PX21	**125**	PC03
18	GND	**54**	PA13	**90**	PB01	**126**	PB13
19	PB28	**55**	VDDCORE	**91**	PX22	**127**	PB14
20	PB29	**56**	PA14	**92**	VDDIO	**128**	TMS
21	PB30	**57**	PA15	**93**	VDDIO	**129**	TCK

Table 6-3. BGA144 Package Pinout A1..M8

	1	2	3	4	5	6	7	8
A	VDDIO	PB07	PB05	PB02	PB03	PB01	PC00	PA28
B	PB08	GND	PB06	PB04	VDDIO	PB00	PC01	VDDPLL
C	PB09	PX33	PA29	PC02	PX28	PX26	PX22	PX21
D	PB11	PB13	PB12	PX30	PX29	PX25	PX24	PX20
E	PB10	VDDIO	PX32	PX31	VDDIO	PX27	PX23	VDDANA
F	PA30	PB14	PX34	PB16	TCK	GND	GND	PX16
G	TMS	PC03	PX36	PX35	PX37	GND	GND	PA16
H	TDO	VDDCORE	PX38	PX39	VDDIO	PA01	PA10	VDDCORE
J	TDI	PB17	PB15	PX00	PX01	PA00	PA03	PA04
K	PC05	PC04	PB19	PB20	PX02	PB29	PB30	PA02
L	PB21	GND	PB18	PB24	VDDOUT	PX04	PB31	VDDIN
M	PB22	PB23	PB25	PB26	PX03	PB27	PB28	RESET_N

Table 6-4. BGA144 Package Pinout A9..M12

	9	10	11	12
A	PA26	PA25	PA24	PA23
B	PA27	PA21	GND	PA22
C	ADVREF	GNDANA	PX19	PA19
D	PA18	PA20	DP	DM
E	PX18	PX17	VDDIO	VBUS
F	PA17	PX15	PA15	PA14
G	PA13	PA12	PA11	NC
H	PX11	PA08	VDDCORE	VDDCORE
J	PX14	PA07	PX13	PA09
K	PX08	GND	PA05	PX12
L	PX06	PX10	GND	PA06
M	PX05	PX07	PX09	VDDIO

Note: NC is not connected.

7. Power Considerations

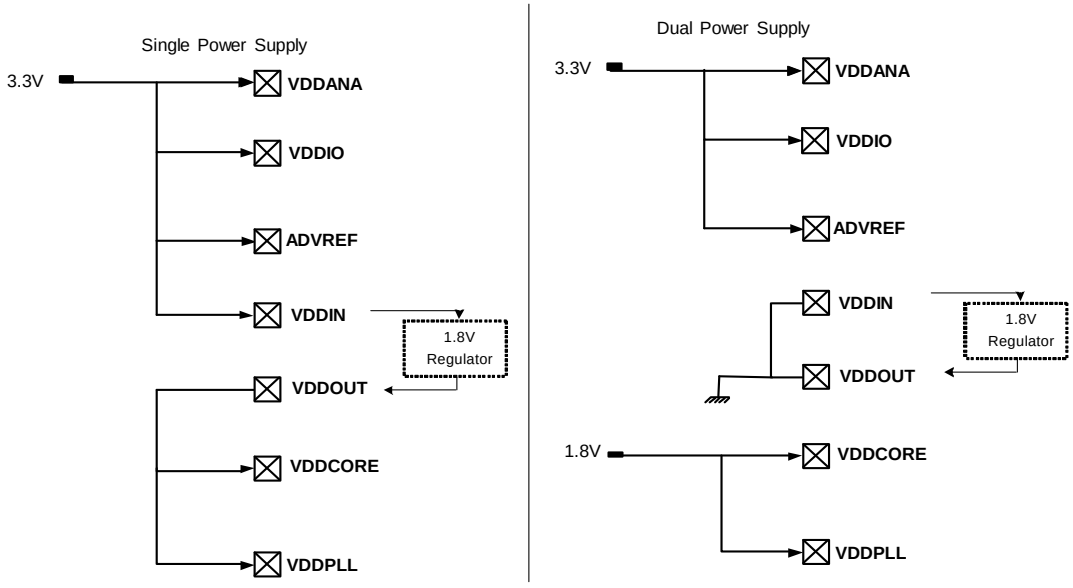
7.1 Power Supplies

The AT32UC3A has several types of power supply pins:

- **VDDIO: Powers I/O lines. Voltage is 3.3V nominal.**
- **VDDANA: Powers the ADC Voltage is 3.3V nominal.**
- **VDDIN: Input voltage for the voltage regulator. Voltage is 3.3V nominal.**
- **VDDCORE: Powers the core, memories, and peripherals. Voltage is 1.8V nominal.**
- **VDDPLL: Powers the PLL. Voltage is 1.8V nominal.**

The ground pins GND are common to VDDCORE, VDDIO, VDDPLL. The ground pin for VDDANA is GNDANA.

Refer to "Power Consumption" on page 44 for power consumption on the various supply pins.



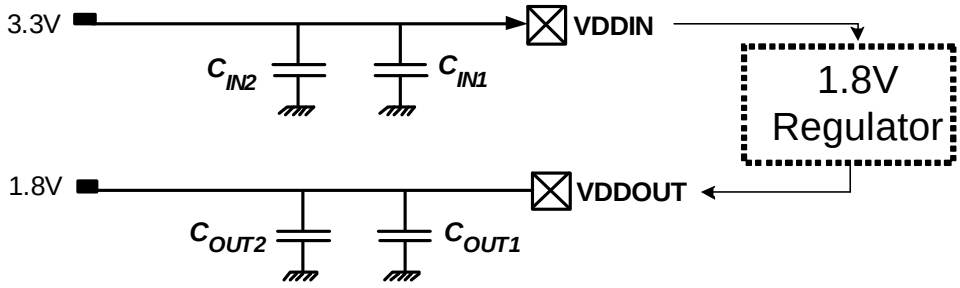
7.2 Voltage Regulator

7.2.1 Single Power Supply

The AT32UC3A embeds a voltage regulator that converts from 3.3V to 1.8V. The regulator takes its input voltage from VDDIN, and supplies the output voltage on VDDOUT. VDDOUT should be externally connected to the 1.8V domains.

Adequate input supply decoupling is mandatory for VDDIN in order to improve startup stability and reduce source voltage drop. Two input decoupling capacitors must be placed close to the chip.

Adequate output supply decoupling is mandatory for VDDOUT to reduce ripple and avoid oscillations. The best way to achieve this is to use two capacitors in parallel between VDDOUT and GND as close to the chip as possible



Refer to Section 12.3 on page 42 for decoupling capacitors values and regulator characteristics

7.2.2 Dual Power Supply

In case of dual power supply, VDDIN and VDDOUT should be connected to ground to prevent from leakage current.

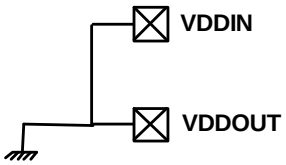


Table 9-2. Flash Memory Parameters

Part Number	Flash Size (*FLASH_PW*)	Number of pages (*FLASH_P*)	Page size (*FLASH_W*)	General Purpose Fuse bits (*FLASH_F*)
AT32UC3A0512	512 Kbytes	1024	128 words	32 fuses
AT32UC3A1512	512 Kbytes	1024	128 words	32 fuses
AT32UC3A0256	256 Kbytes	512	128 words	32 fuses
AT32UC3A1256	256 Kbytes	512	128 words	32 fuses
AT32UC3A1128	128 Kbytes	256	128 words	32 fuses
AT32UC3A0128	128 Kbytes	256	128 words	32 fuses

9.3 Bus Matrix Connections

Accesses to unused areas returns an error result to the master requesting such an access.

The bus matrix has the several masters and slaves. Each master has its own bus and its own decoder, thus allowing a different memory mapping per master. The master number in the table below can be used to index the HMATRIX control registers. For example, MCFG0 is associated with the CPU Data master interface.

Table 9-3. High Speed Bus masters

Master 0	CPU Data
Master 1	CPU Instruction
Master 2	CPU SAB
Master 3	PDCA
Master 4	MACB DMA
Master 5	USBB DMA

Each slave has its own arbiter, thus allowing a different arbitration per slave. The slave number in the table below can be used to index the HMATRIX control registers. For example, SCFG3 is associated with the Internal SRAM Slave Interface.

Table 9-4. High Speed Bus slaves

Slave 0	Internal Flash
Slave 1	HSB-PB Bridge 0
Slave 2	HSB-PB Bridge 1
Slave 3	Internal SRAM
Slave 4	USBB DPRAM
Slave 5	EBI

Table 10-3. Interrupt Request Signal Map

9	0	Serial Peripheral Interface	SPI0
10	0	Serial Peripheral Interface	SPI1
11	0	Two-wire Interface	TWI
12	0	Pulse Width Modulation Controller	PWM
13	0	Synchronous Serial Controller	SSC
14	0	Timer/Counter	TC0
	1	Timer/Counter	TC1
	2	Timer/Counter	TC2
15	0	Analog to Digital Converter	ADC
16	0	Ethernet MAC	MACB
17	0	USB 2.0 OTG Interface	USBB
18	0	SDRAM Controller	SDRAMC
19	0	Audio Bitstream DAC	DAC

10.4 Clock Connections

10.4.1 Timer/Counters

Each Timer/Counter channel can independently select an internal or external clock source for its counter:

Table 10-4. Timer/Counter clock connections

Source	Name	Connection
Internal	TIMER_CLOCK1	32 KHz Oscillator
	TIMER_CLOCK2	PBA clock / 2
	TIMER_CLOCK3	PBA clock / 8
	TIMER_CLOCK4	PBA clock / 32
	TIMER_CLOCK5	PBA clock / 128
External	XC0	See Section 10.7
	XC1	
	XC2	

10.4.2 USARTs

Each USART can be connected to an internally divided clock:

Table 10-5. USART clock connections

USART	Source	Name	Connection
0	Internal	CLK_DIV	PBA clock / 8
1			
2			
3			

Table 10-9. GPIO Controller Function Multiplexing

7	11	PB24	GPIO 56	TC - B0	USART1 - DSR	
8	13	PB25	GPIO 57	TC - A1	USART1 - DTR	
9	14	PB26	GPIO 58	TC - B1	USART1 - RI	
10	15	PB27	GPIO 59	TC - A2	PWM - PWM[4]	
14	19	PB28	GPIO 60	TC - B2	PWM - PWM[5]	
15	20	PB29	GPIO 61	USART2 - RXD	PM - GCLK[1]	EBI - NCS[2]
16	21	PB30	GPIO 62	USART2 - TXD	PM - GCLK[2]	EBI - SDCS
17	22	PB31	GPIO 63	USART2 - CLK	PM - GCLK[3]	EBI - NWAIT
63	85	PC00	GPIO 64			
64	86	PC01	GPIO 65			
85	124	PC02	GPIO 66			
86	125	PC03	GPIO 67			
93	132	PC04	GPIO 68			
94	133	PC05	GPIO 69			
	1	PX00	GPIO 100	EBI - DATA[10]	USART0 - RXD	
	2	PX01	GPIO 99	EBI - DATA[9]	USART0 - TXD	
	4	PX02	GPIO 98	EBI - DATA[8]	USART0 - CTS	
	10	PX03	GPIO 97	EBI - DATA[7]	USART0 - RTS	
	12	PX04	GPIO 96	EBI - DATA[6]	USART1 - RXD	
	24	PX05	GPIO 95	EBI - DATA[5]	USART1 - TXD	
	26	PX06	GPIO 94	EBI - DATA[4]	USART1 - CTS	
	31	PX07	GPIO 93	EBI - DATA[3]	USART1 - RTS	
	33	PX08	GPIO 92	EBI - DATA[2]	USART3 - RXD	
	35	PX09	GPIO 91	EBI - DATA[1]	USART3 - TXD	
	38	PX10	GPIO 90	EBI - DATA[0]	USART2 - RXD	
	40	PX11	GPIO 109	EBI - NWE1	USART2 - TXD	
	42	PX12	GPIO 108	EBI - NWE0	USART2 - CTS	
	44	PX13	GPIO 107	EBI - NRD	USART2 - RTS	
	46	PX14	GPIO 106	EBI - NCS[1]		TC - A0
	59	PX15	GPIO 89	EBI - ADDR[19]	USART3 - RTS	TC - B0
	61	PX16	GPIO 88	EBI - ADDR[18]	USART3 - CTS	TC - A1
	63	PX17	GPIO 87	EBI - ADDR[17]		TC - B1
	65	PX18	GPIO 86	EBI - ADDR[16]		TC - A2
	67	PX19	GPIO 85	EBI - ADDR[15]	EIM - SCAN[0]	TC - B2
	87	PX20	GPIO 84	EBI - ADDR[14]	EIM - SCAN[1]	TC - CLK0
	89	PX21	GPIO 83	EBI - ADDR[13]	EIM - SCAN[2]	TC - CLK1
	91	PX22	GPIO 82	EBI - ADDR[12]	EIM - SCAN[3]	TC - CLK2
	95	PX23	GPIO 81	EBI - ADDR[11]	EIM - SCAN[4]	
	97	PX24	GPIO 80	EBI - ADDR[10]	EIM - SCAN[5]	

12.2 DC Characteristics

The following characteristics are applicable to the operating temperature range: T_A = -40°C to 85°C, unless otherwise specified and are certified for a junction temperature up to T_J = 100°C.

Table 12-1. DC Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
$V_{VDDCORE}$	DC Supply Core		1.65		1.95	V
V_{VDDPLL}	DC Supply PLL		1.65		1.95	V
V_{VDDIO}	DC Supply Peripheral I/Os		3.0		3.6	V
V_{REF}	Analog reference voltage		2.6		3.6	V
V_{IL}	Input Low-level Voltage		-0.3		+0.8	V
V_{IH}	Input High-level Voltage	All GPIOS except for PC00, PC01, PC02, PC03, PC04, PC05.	2.0		5.5V	V
		PC00, PC01, PC02, PC03, PC04, PC05.	2.0		3.6V	V
V_{OL}	Output Low-level Voltage	I_{OL}=-4mA for PA0-PA20, PB0, PB4-PB9, PB11-PB18, PB24-PB26, PB29-PB31, PX0-PX39			0.4	V
		I_{OL}=-8mA for PA21-PA30, PB1-PB3, PB10, PB19-PB23, PB27-PB28, PC0-PC5			0.4	V
V_{OH}	Output High-level Voltage	I_{OH}=4mA for PA0-PA20, PB0, PB4-PB9, PB11-PB18, PB24-PB26, PB29-PB31, PX0-PX39	V_{VDDIO}-0.4			V
		I_{OH}=8mA for PA21-PA30, PB1-PB3, PB10, PB19-PB23, PB27-PB28, PC0-PC5	V_{VDDIO}-0.4			V
I_{OL}	Output Low-level Current	PA0-PA20, PB0, PB4-PB9, PB11-PB18, PB24-PB26, PB29-PB31, PX0-PX39			-4	mA
		PA21-PA30, PB1-PB3, PB10, PB19-PB23, PB27-PB28, PC0-PC5			-8	mA
I_{OH}	Output HIgh-level Current	PA0-PA20, PB0, PB4-PB9, PB11-PB18, PB24-PB26, PB29-PB31, PX0-PX39			4	mA
		PA21-PA30, PB1-PB3, PB10, PB19-PB23, PB27-PB28, PC0-PC5			8	mA
I_{LEAK}	Input Leakage Current	Pullup resistors disabled			1	µA
C_{IN} Input Capacitance		TQFP100 Package		7		pF
		LQFP144 Package		7		pF
R_{PULLUP}	Pull-up Resistance	All GPIO and RESET_N pin.	10K	15K		Ohm

12.3 Regulator characteristics

Table 12-2. Electrical characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{VDDIN}	Supply voltage (input)		3	3.3	3.6	V
V_{VDDOUT}	Supply voltage (output)		1.81	1.85	1.89	V
I_{OUT}	Maximum DC output current with $V_{VDDIN = 3.3V}$				100	mA
	Maximum DC output current with $V_{VDDIN = 2.7V}$				90	mA
I_{SCR}	Static Current of internal regulator	Low Power mode (stop, deep stop or static) at T_A =25°C		10		µA

Table 12-3. Decoupling requirements

Symbol	Parameter	Condition	Typ.	Techno.	Units
C_{IN1}	Input Regulator Capacitor 1		1	NPO	nF
C_{IN2}	Input Regulator Capacitor 2		4.7	X7R	uF
C_{OUT1}	Output Regulator Capacitor 1		470	NPO	pF
C_{OUT2}	Output Regulator Capacitor 2		2.2	X7R	uF

12.4 Analog characteristics

Table 12-4. Electrical characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{ADVREF}	Analog voltage reference (input)		2.6		3.6	V

Table 12-5. Decoupling requirements

Symbol	Parameter	Condition	Typ.	Techno.	Units
C_{VREF1}	Voltage reference Capacitor 1		10	-	nF
C_{VREF2}	Voltage reference Capacitor 2		1	-	uF

12.4.1 BOD

Table 12-6. BODLEVEL Values

BODLEVEL Value	Typ.	Typ.	Typ.	Units.
00 0000b	1.40	1.47	1.55	V
01 0111b	1.45	1.52	1.6	V
01 1111b	1.55	1.6	1.65	V
10 0111b	1.65	1.69	1.75	V

The values in Table 12-6 describes the values of the BODLEVEL in the flash FGPFR register.

Table 12-7. BOD Timing

Symbol	Parameter	Test Conditions	Typ.	Max.	Units.
T_{BOD}	Minimum time with VDDCORE < VBOD to detect power failure	Falling VDDCORE from 1.8V to 1.1V	300	800	ns

12.4.2 POR

Table 12-8. Electrical Characteristic

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units.
V_{DDRR}	VDDCORE rise rate to ensure power-on-reset		0.01			V/ms
V_{SSFR}	VDDCORE fall rate to ensure power-on-reset		0.01		400	V/ms
V_{POR+}	Rising threshold voltage: voltage up to which device is kept under reset by POR on rising VDDCORE	Rising VDDCORE: $V_{RESTART}$ -> V_{POR+}	1.35	1.5	1.6	V
V_{POR-}	Falling threshold voltage: voltage when POR resets device on falling VDDCORE	Falling VDDCORE: 1.8V -> V_{POR+}	1.25	1.3	1.4	V
$V_{RESTART}$	On falling VDDCORE, voltage must go down to this value before supply can rise again to ensure reset signal is released at V_{POR+}	Falling VDDCORE: 1.8V -> $V_{RESTART}$	-0.1		0.5	V
T_{POR}	Minimum time with VDDCORE < V_{POR-}	Falling VDDCORE: 1.8V -> 1.1V		15		us
T_{RST}	Time for reset signal to be propagated to system			200	400	us

12.9 EBI Timings

These timings are given for worst case process, T = 85·C, VDDCORE = 1.65V, VDDIO = 3V and 40 pF load capacitance.

Table 12-22. SMC Clock Signal.

Symbol	Parameter	Max[1]	Units
$1/(t_{CPSMC})$	SMC Controller Clock Frequency	$1/(t_{cpcpu})$	MHz

Note: 1. The maximum frequency of the SMC interface is the same as the max frequency for the HSB.

Table 12-23. SMC Read Signals with Hold Settings

Symbol	Parameter	Min	Units
NRD Controlled (READ_MODE = 1)			
SMC_1	Data Setup before NRD High	12	ns
SMC_2	Data Hold after NRD High	0	
SMC_3	NRD High to NBS0/A0 Change[1]	nrd hold length * t_{CPSMC} - 1.3	
SMC_4	NRD High to NBS1 Change[1]	nrd hold length * t_{CPSMC} - 1.3	
SMC_5	NRD High to NBS2/A1 Change[1]	nrd hold length * t_{CPSMC} - 1.3	
SMC_6	NRD High to NBS3 Change[1]	nrd hold length * t_{CPSMC} - 1.3	
SMC_7	NRD High to A2 - A25 Change[1]	nrd hold length * t_{CPSMC} - 1.3	
SMC_8	NRD High to NCS Inactive[1]	(nrd hold length - ncs rd hold length) * t_{CPSMC} - 2.3	
SMC_9	NRD Pulse Width	nrd pulse length * t_{CPSMC} - 1.4	
NRD Controlled (READ_MODE = 0)			
SMC_{10}	Data Setup before NCS High	11.5	ns
SMC_{11}	Data Hold after NCS High	0	
SMC_{12}	NCS High to NBS0/A0 Change[1]	ncs rd hold length * t_{CPSMC} - 2.3	
SMC_{13}	NCS High to NBS0/A0 Change[1]	ncs rd hold length * t_{CPSMC} - 2.3	
SMC_{14}	NCS High to NBS2/A1 Change[1]	ncs rd hold length * t_{CPSMC} - 2.3	
SMC_{15}	NCS High to NBS3 Change[1]	ncs rd hold length * t_{CPSMC} - 2.3	
SMC_{16}	NCS High to A2 - A25 Change[1]	ncs rd hold length * t_{CPSMC} - 4	
SMC_{17}	NCS High to NRD Inactive[1]	ncs rd hold length - nrd hold length)* t_{CPSMC} - 1.3	
SMC_{18}	NCS Pulse Width	ncs rd pulse length * t_{CPSMC} - 3.6	

Note: 1. hold length = total cycle duration - setup duration - pulse duration. “hold length” is for “ncs rd hold length” or “nrd hold length”.

Table 12-30. SPI Timings

Symbol	Parameter	Conditions	Min	Max	Units
SPI_0	MISO Setup time before SPCK rises (master)	3.3V domain(1)	22 + (t_{CPMCK})/2(2)		ns
SPI_1	MISO Hold time after SPCK rises (master)	3.3V domain(1)	0		ns
SPI_2	SPCK rising to MOSI Delay (master)	3.3V domain(1)		7	ns
SPI_3	MISO Setup time before SPCK falls (master)	3.3V domain(1)	22 + (t_{CPMCK})/2(2)		ns
SPI_4	MISO Hold time after SPCK falls (master)	3.3V domain (1)	0		ns
SPI_5	SPCK falling to MOSI Delay (master)	3.3V domain (1)		7	ns
SPI_6	SPCK falling to MISO Delay (slave)	3.3V domain (1)		26.5	ns
SPI_7	MOSI Setup time before SPCK rises (slave)	3.3V domain (1)	0		ns
SPI_8	MOSI Hold time after SPCK rises (slave)	3.3V domain (1)	1.5		ns
SPI_9	SPCK rising to MISO Delay (slave)	3.3V domain (1)		27	ns
SPI_{10}	MOSI Setup time before SPCK falls (slave)	3.3V domain (1)	0		ns
SPI_{11}	MOSI Hold time after SPCK falls (slave)	3.3V domain (1)	1		ns

Notes: 1. 3.3V domain: V_{VDDIO} from 3.0V to 3.6V, maximum external capacitor = 40 pF.
2. t_{CPMCK}: Master Clock period in ns.

12.12 MACB Characteristics

Table 12-31. Ethernet MAC Signals

Symbol	Parameter	Conditions	Min (ns)	Max (ns)
$EMAC_1$	Setup for EMDIO from EMDC rising	Load: 20pF(2)		
$EMAC_2$	Hold for EMDIO from EMDC rising	Load: 20pF(2)		
$EMAC_3$	EMDIO toggling from EMDC falling	Load: 20pF(2)		

Notes: 1. f: MCK frequency (MHz)
2. V_{VDDIO} from 3.0V to 3.6V, maximum external capacitor = 20 pF

Table 12-32. Ethernet MAC MII Specific Signals

Symbol	Parameter	Conditions	Min (ns)	Max (ns)
$EMAC_4$	Setup for ECOL from ETXCK rising	Load: 20pF (1)	3	
$EMAC_5$	Hold for ECOL from ETXCK rising	Load: 20pF (1)	0	
$EMAC_6$	Setup for ECRS from ETXCK rising	Load: 20pF (1)	3	
$EMAC_7$	Hold for ECRS from ETXCK rising	Load: 20pF (1)	0	
$EMAC_8$	ETXER toggling from ETXCK rising	Load: 20pF (1)		15
$EMAC_9$	ETXEN toggling from ETXCK rising	Load: 20pF (1)		15
$EMAC_{10}$	ETX toggling from ETXCK rising	Load: 20pF (1)		15
$EMAC_{11}$	Setup for ERX from ERXCK	Load: 20pF (1)	1	

13. Mechanical Characteristics

13.1 Thermal Considerations

13.1.1 Thermal Data

Table 13-1 summarizes the thermal resistance data depending on the package.

Table 13-1. Thermal Resistance Data

Symbol	Parameter	Condition	Package	Typ	Unit
θ_{JA}	Junction-to-ambient thermal resistance	Still Air	TQFP100	43.4	°C/W
θ_{JC}	Junction-to-case thermal resistance		TQFP100	5.5	
θ_{JA}	Junction-to-ambient thermal resistance	Still Air	LQFP144	39.8	°C/W
θ_{JC}	Junction-to-case thermal resistance		LQFP144	8.9	

13.1.2 Junction Temperature

The average chip-junction temperature, T_J, in °C can be obtained from the following:

1. $T_J = T_A + (P_D \times \theta_{JA})$
2. $T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$

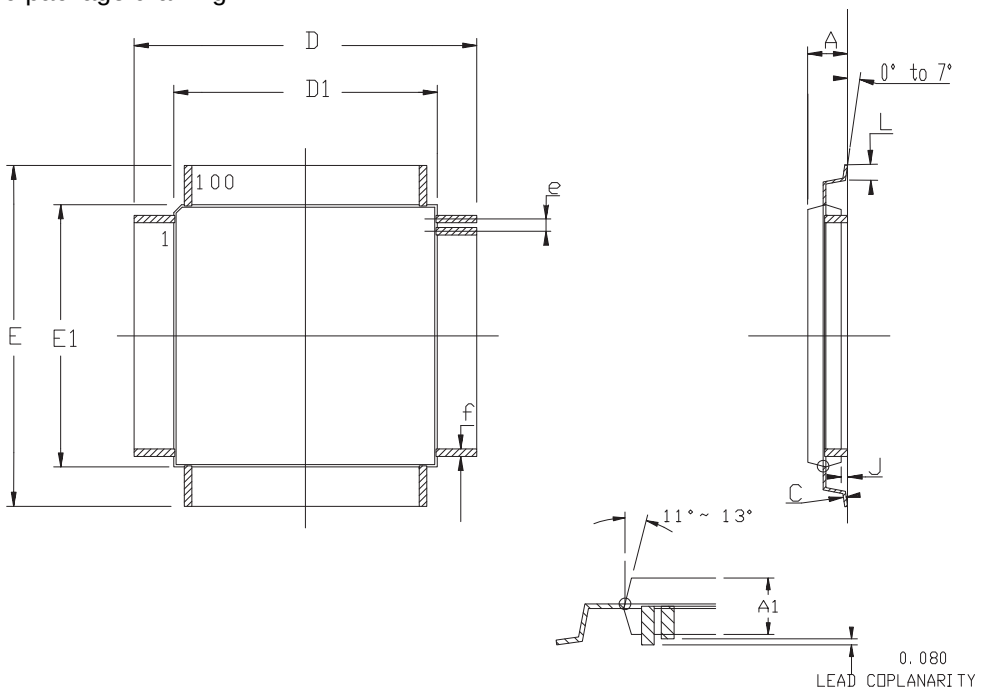
where:

- θ_{JA} = package thermal resistance, Junction-to-ambient (°C/W), provided in Table 13-1 on page 64.
- θ_{JC} = package thermal resistance, Junction-to-case thermal resistance (°C/W), provided in Table 13-1 on page 64.
- $\theta_{HEAT\ SINK}$ = cooling device thermal resistance (°C/W), provided in the device datasheet.
- P_D = device power consumption (W) estimated from data provided in the section "Power Consumption" on page 44.
- T_A = ambient temperature (°C).

From the first equation, the user can derive the estimated lifetime of the chip and decide if a cooling device is necessary or not. If a cooling device is to be fitted on the chip, the second equation should be used to compute the resulting average chip-junction temperature T_J in °C.

13.2 Package Drawings

Figure 13-1. TQFP-100 package drawing



	MM		INCH	
	Min	Max	Min	Max
A	----	1.20	----	.047
A1	0.95	1.05	.037	.041
C	0.09	0.20	.004	.008
D	16.00 BSC		.630 BSC	
D1	14.00 BSC		.551 BSC	
E	16.00 BSC		.630 BSC	
E1	14.00 BSC		.551 BSC	
J	0.05	0.15	.002	.006
L	0.45	0.75	.018	.030
e	0.50 BSC		.020 BSC	
f	0.17	0.27	.007	.011

Table 13-2. Device and Package Maximum Weight

500	mg

Table 13-3. Package Characteristics

Moisture Sensitivity Level	Jdec J-STD0-20D - MSL 3

Table 13-4. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

13.3 Soldering Profile

Table 13-11 gives the recommended soldering profile from J-STD-20.

Table 13-11. Soldering Profile

Profile Feature	Green Package
Average Ramp-up Rate (217°C to Peak)	3°C/sec
Preheat Temperature 175°C ±25°C	Min. 150 °C, Max. 200 °C
Time Maintained Above 217°C	60-150 sec
Time within 5·C of Actual Peak Temperature	30 sec
Peak Temperature Range	260 °C
Ramp-down Rate	6 °C/sec
Time 25·C to Peak Temperature	Max. 8 minutes

Note: It is recommended to apply a soldering temperature higher than 250°C.

A maximum of three reflow passes is allowed per component.

None.

15.2.9 USART

1. **ISO7816 info register US_NER cannot be read**
   The NER register always returns zero.
   Fix/Workaround
   None

15.2.10 Processor and Architecture

1. **LDM instruction with PC in the register list and without ++ increments Rp**
   For LDM with PC in the register list: the instruction behaves as if the ++ field is always set, ie the pointer is always updated. This happens even if the ++ field is cleared. Specifically, the increment of the pointer is done in parallel with the testing of R12.
   Fix/Workaround
   None.

2. **RETE instruction does not clear SREG[L] from interrupts.**
   The RETE instruction clears SREG[L] as expected from exceptions.
   Fix/Workaround
   When using the STCOND instruction, clear SREG[L] in the stacked value of SR before returning from interrupts with RETE.

3. **Exceptions when system stack is protected by MPU**
   RETS behaves incorrectly when MPU is enabled and MPU is configured so that system stack is not readable in unprivileged mode.
   Fix/Woraround
   Workaround 1: Make system stack readable in unprivileged mode,
   or
   Workaround 2: Return from supervisor mode using rete instead of rets. This requires :
   1. Changing the mode bits from 001b to 110b before issuing the instruction. Updating the mode bits to the desired value must be done using a single mtsr instruction so it is done atomically. Even if this step is described in general as not safe in the UC technical reference guide, it is safe in this very specific case.
   2. Execute the RETE instruction.

When multiple CS are in use, if one of the baudrate equals 1, the other must also equal 1 if CPOL=1 and CPHA=0.

4. **SPI Glitch on RXREADY flag in slave mode when enabling the SPI or during the first transfer**
   In slave mode, the SPI can generate a false RXREADY signal during enabling of the SPI or during the first transfer.

   Fix/Workaround
   1. Set slave mode, set required CPOL/CPHA.
   2. Enable SPI.
   3. Set the polarity CPOL of the line in the opposite value of the required one.
   4. Set the polarity CPOL to the required one.
   5. Read the RXHOLDING register.

   Transfers can now befin and RXREADY will now behave as expected.

5. **SPI Disable does not work in Slave mode**
   Fix/workaround
   Read the last received data then perform a Software reset.

15.3.4 Power Manager

1. **If the BOD level is higher than VDDCORE, the part is constantly under reset**
   If the BOD level is set to a value higher than VDDCORE and enabled by fuses, the part will be in constant reset.

   Fix/Workaround
   Apply an external voltage on VDDCORE that is higher than the BOD level and is lower than VDDCORE max and disable the BOD.

15.3.5 Flashc

1. **On AT32UC3A0512 and AT32UC3A1512, corrupted read in flash after FLASHC WP, EP, EA, WUP, EUP commands may happen**
   - After a FLASHC Write Page (WP) or Erase Page (EP) command applied to a page in a given half of the flash (first or last 256 kB of flash), reading (data read or code fetch) the other half of the flash may fail. This may lead to an exception or to other errors derived from this corrupted read access.
   - After a FLASHC Erase All (EA) command, reading (data read or code fetch) the flash may fail. This may lead to an exception or to other errors derived from this corrupted read access.
   - After a FLASHC Write User Page (WUP) or Erase User Page (EUP) command, reading (data read or code fetch) the second half (last 256 kB) of the flash may fail. This may lead to an exception or to other errors derived from this corrupted read access.

   Fix/Workaround
   Flashc WP, EP, EA, WUP, EUP commands: these commands must be issued from RAM or through the EBI. After these commands, read twice one flash page initialized to 00h in each half part of the flash.

15.3.6 PDCA

1. **Wrong PDCA behavior when using two PDCA channels with the same PID.**

specific case.
2. Execute the RETE instruction.

Fix/Workaround

In PLL0/1 Control register, the bit 7 should be set in order to prevent unexpected behaviour.

4. **Peripheral Bus A maximum frequency is 33MHz instead of 66MHz.**
   Fix/Workaround
   Do not set PBA frequency higher than 33 MHz.

5. **PCx pins go low in stop mode**
   In sleep mode stop all PCx pins will be controlled by GPIO module instead of oscillators. This can cause drive contention on the XINx in worst case.

   Fix/Workaround
   Before entering stop mode set all PCx pins to input and GPIO controlled.

6. **On some rare parts, the maximum HSB and CPU speed is 50MHz instead of 66MHz.**
   Fix/Workaround
   Do not set the HSB/CPU speed higher than 50MHz when the firmware generate exceptions.

7. **If the BOD level is higher than VDDCORE, the part is constantly under reset**
   If the BOD level is set to a value higher than VDDCORE and enabled by fuses, the part will be in constant reset.

   Fix/Workaround
   Apply an external voltage on VDDCORE that is higher than the BOD level and is lower than VDDCORE max and disable the BOD.

8. **System Timer mask (Bit 16) of the PM CPUMASK register is not available.**
   Fix/Workaround
   Do not use this bit.

15.5.9 HMatrix

1. **HMatrix fixed priority arbitration does not work**
   Fixed priority arbitration does not work.

   Fix/Workaround
   Use Round-Robin arbitration instead.

15.5.10 ADC

1. **ADC possible miss on DRDY when disabling a channel**
   The ADC does not work properly when more than one channel is enabled.

   Fix/Workaround
   Do not use the ADC with more than one channel enabled at a time.

2. **ADC OVRE flag sometimes not reset on Status Register read**
   The OVRE flag does not clear properly if read simultaneously to an end of conversion.

   Fix/Workaround
   None.

3. **Sleep Mode activation needs additional A to D conversion**

16.6 Rev. C – 10/07

1. Updated ”Signal Description List” on page 8. Removed RXDN and TXDN from USART section.
2. Updated ”Errata” on page 70. Rev G replaced by rev H.

16.7 Rev. B – 10/07

1. Updated ”Features” on page 1.
2. Update ”Blockdiagram” on page 4 with local bus.
3. Updated ”Peripherals” on page 34 with local bus.
4. Add SPI feature in ”Universial Synchronous/Asynchronous Receiver/Transmitter (USART)” on page 315.
5. Updated ”USB On-The-Go Interface (USBB)” on page 517.
6. Updated ”JTAG and Boundary Scan” on page 750 with programming procedure .
7. Add description for silicon Rev G.

16.8 Rev. A – 03/07

1. Initial revision.